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United States Patent [19]

Kimura

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[54] **CAP FOR USE IN A SEMICONDUCTOR WAFER HEAT PROCESSING APPARATUS**

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[73] Assignee: **Tokyo Electron Limited**, Tokyo-to, Japan

[**] Term: **14 Years**

[21] Appl. No.: **83,424**

[22] Filed: **Feb. 5, 1998**

[30] **Foreign Application Priority Data**

Aug. 20, 1997 [JP] Japan 9-65100

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; D15/144, D15/144.1, 199; 414/935–941, 217, 147; 437/247, 946

[56] **References Cited**

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Primary Examiner—Brian N.. Vinson

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[57] **CLAIM**

I claim the ornamental design for cap for use in a semiconductor wafer heat processing apparatus, as shown and described.

DESCRIPTION

FIG. **1** a perspective view of a cap for use in a semiconductor wafer heat processing apparatus;

FIG. **2** a top plan view thereof;

FIG. **3** a bottom plan view thereof;

FIG. **4** a front elevational view thereof; and,

FIG. **5** a cross-sectional view taken along line V—V in FIG. 2;

1 Claim, 1 Drawing Sheet

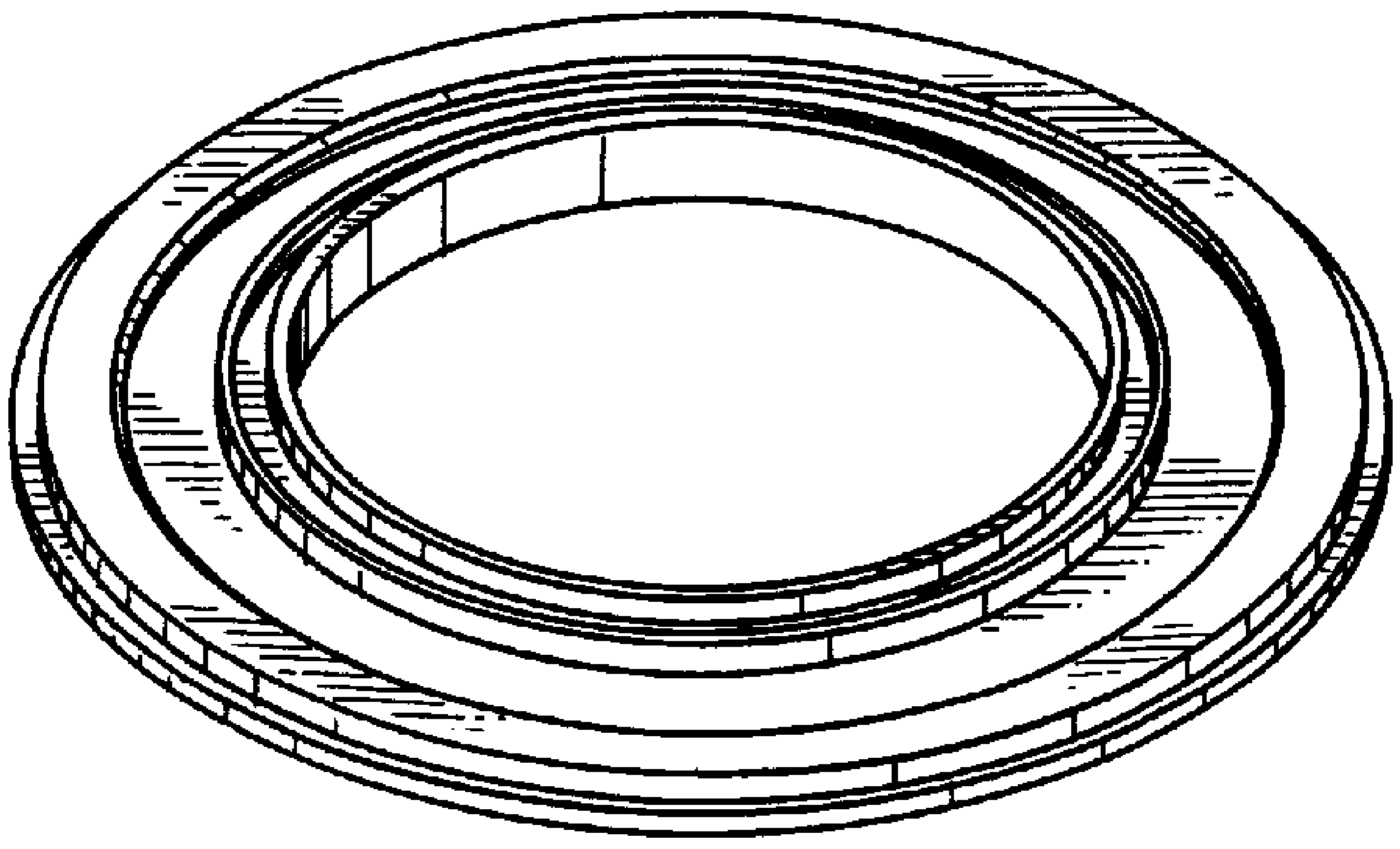

FIG. 1

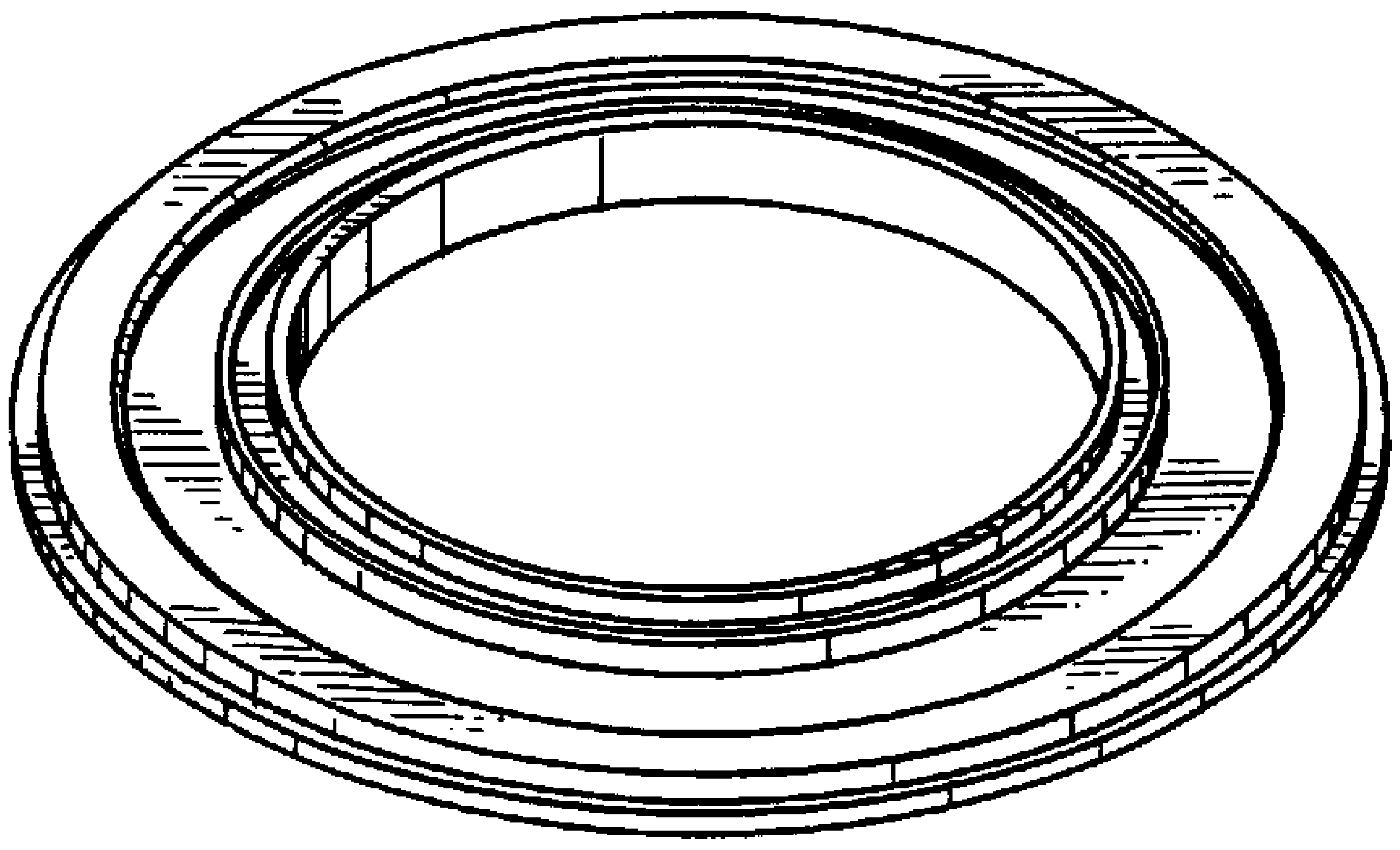

FIG. 2

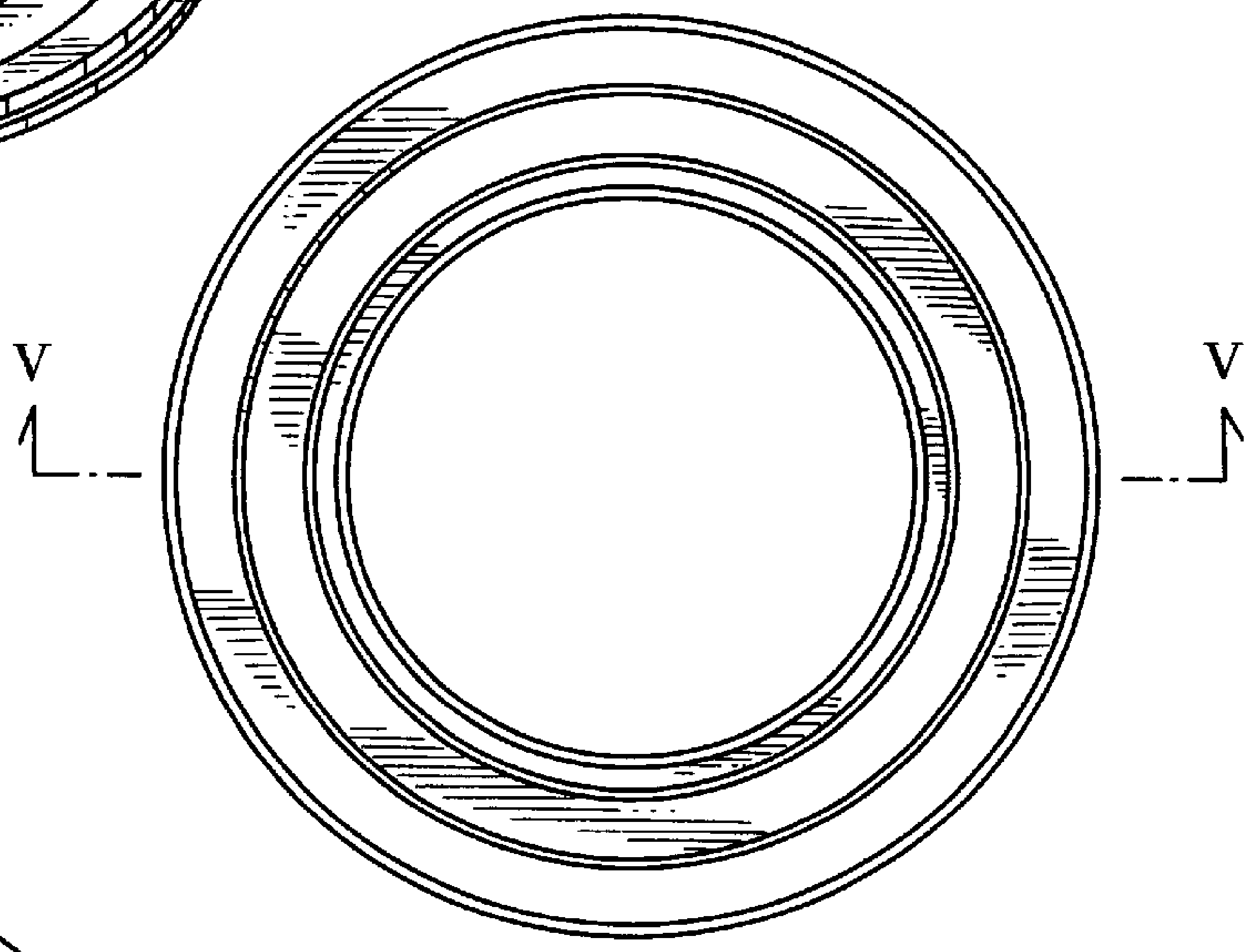

FIG. 3

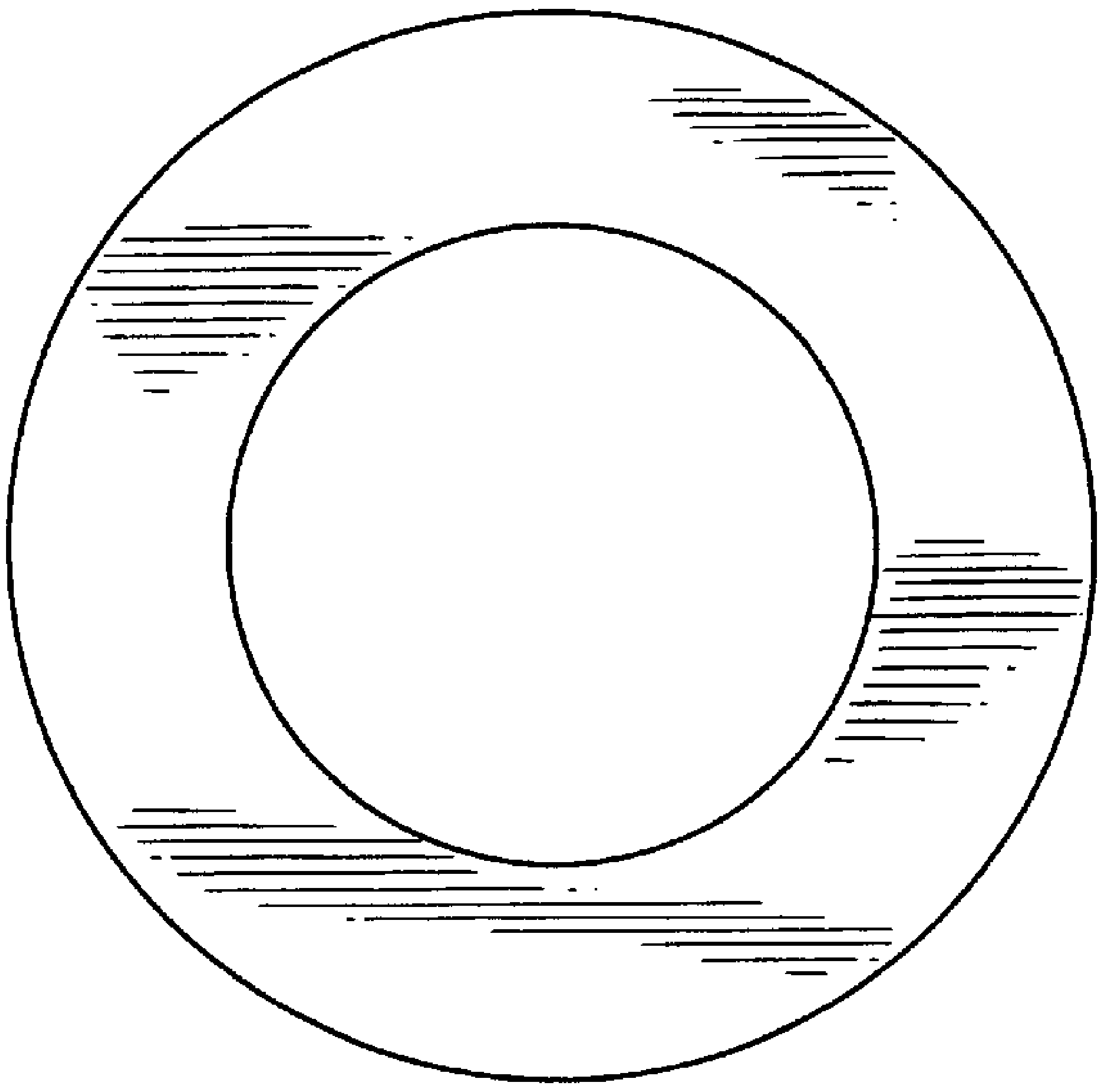

FIG. 4

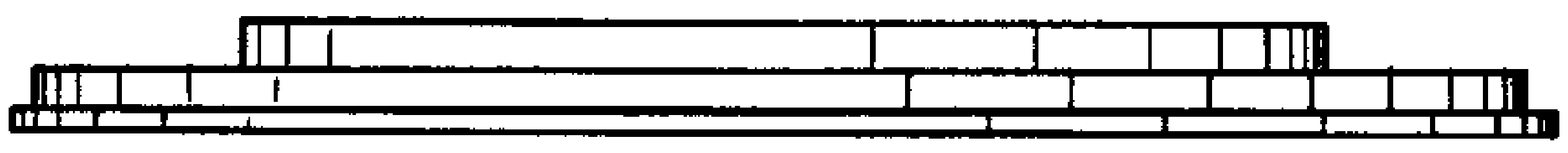

FIG. 5